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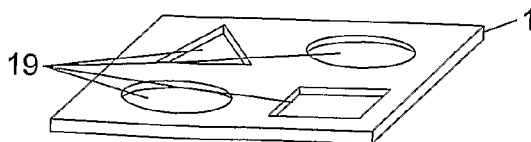
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(54) Title: ELECTROFORMED COMPONENT MANUFACTURE



(57) Abstract: The present invention relates to a method of forming an electroformed component (1). The method includes forming a conductive seed layer (5) on a substrate (3) by spraying at least a first solution onto the substrate (3) to form a first conductive layer. A patterned resist (11) is provided over the conductive seed layer (5) and the component (1) is then electroformed. The present invention also relates to electroformed components (1) and apparatus for forming electroformed components (1).

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